

IN THE CLAIMS:

Please CANCEL claims 65-69 and 74 without prejudice to or disclaimer of the recited subject matter.

Please AMEND claims 70 and 72, and ADD new claims 78-80, as follows. Note that all the claims currently pending in this application, including those not currently amended, have been reproduced below for the Examiner's convenience.

1-69. (Cancelled)

70. (Currently Amended) An exposure apparatus comprising:

an illumination system for illuminating a pattern on a mask with luminous light from a light source;

a projection system for projecting the pattern onto a wafer; and

an optical element, which has a titanium oxide film formed on only a periphery of its surface, wherein said optical element comprises a mirror.

71. (Previously Presented) An exposure apparatus according to claim 70, wherein a titanium oxide film is provided on the surface of at least one region of a supporting unit for supporting at least one optical unit.

72. (Currently Amended) An exposure apparatus ~~according to claim 70~~ comprising:  
an illumination system for illuminating a pattern on a mask with luminous light  
from a light source;  
a projection system for projecting the pattern onto a wafer; and  
an optical element, which has a titanium oxide film formed on only a periphery  
of its surface, wherein said optical element comprises at least one of a diaphragm, a shutter,  
and a lens barrel.

73. (Previously Presented) An exposure apparatus according to claim 70, wherein said  
optical element comprises at least one of a lens, a mirror, a prism, a filter, a diffuser, a  
diffraction optical element, and an optical integrator.

74. (Cancelled)

75. (Previously Presented) An exposure apparatus according to claim 70, wherein said  
titanium oxide film is provided on the surface of a portion of a region of said optical  
element in which light passes through.

76. (Previously Presented) An exposure apparatus according to claim 70, wherein  
exposure is performed while the pattern on the mask and the wafer are synchronously  
scanned.

77. (Previously Presented) A device manufacturing method comprising:  
an exposing step for exposing the wafer by using the exposure apparatus  
according to claim 70; and  
a developing step for developing the exposed wafer.

78. (New) An exposure apparatus according to claim 70, wherein the optical element  
is included in the projection system.

79. (New) A device manufacturing method comprising:  
an exposing step for exposing a wafer by using the exposure apparatus  
according to claim 72; and  
a developing step for developing the exposed wafer.

80. (New) An exposure apparatus according to claim 72, wherein the optical element  
is included in the projection system.